

BL 1005 Series Multilayer Chip Baluns

Features

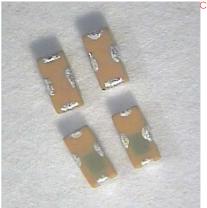
Monolithic SMD with small, low-profile and light-weight type.

✤ RoHS compliant

Applications

✤ 758 ~ 821 MHz wireless communication systems.

Specifications



| Part Number | Frequency Range (MHz) | Unbalanced Impedance (ohm) | Balance Impedance (ohm) | Insertion Loss (dB) | Return Loss (dB) | Phase Difference (degree) | Amplitude Difference (dB) |
|--------------------|-----------------------------|----------------------------------|-------------------------------|---------------------------|---------------------|---------------------------------|---------------------------------|
| BL1005- 10D0790 | 758 ~ 821 | 50 | 100 | 0.8max. | 15 min. | 180 ± 10 | 2 max. |

Q'ty/Reel (pcs): 10000Operating Temperature Range: -40 ~ +85 °CStorage Temperature Range: -40 ~ +85 °CStorage Period: 12 months max.**12 months in vacuum sealed bagand 1 week after opened. Please keep unused parts in vacuum sealed bags.Solder Paste: SAC 305 type is recommended.Power Capacity: 3W max.

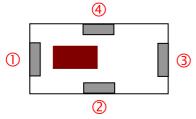
Part Number

| <u>BL</u> | <u>1005</u> | - | <u>10</u> | <u>D</u> | <u>0790</u> | | <u>/LF</u> |
|-----------|-------------|---|-----------|----------|-------------|---|------------|
| 1 | 2 | | 3 | 4 | (5) | 6 | \bigcirc |

| ① Туре | BL : Balun | ② Dimensions (L×W) | 1.0 × 0.5 mm | |
|-------------------|---------------|-----------------------|---------------------------|--|
| 3 Balun Impedance | 10:100 ohnm | Specification Code | D | |
| S Frequency Range | 0790=790MHz | 6 Packaging | T: Tape & Reel B: Bulk | |
| Soldering | /LF=lead-free | | | |



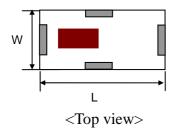
Terminal Configuration



| No. | Terminal Name | No. | Terminal Name |
|-----|-----------------|-----|---------------|
| 0 | Balanced Port | 3 | Balanced Port |
| 2 | Unbalanced Port | 4 | GND |

Dimensions and Recommended PC Board Pattern

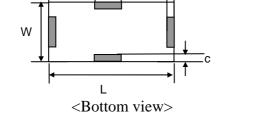
Unit : mm



а

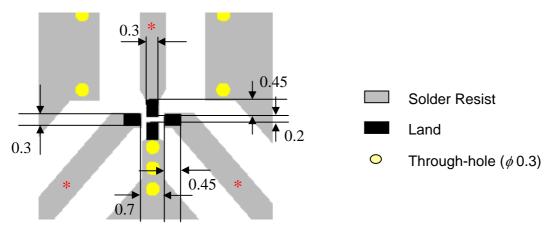


<Side view>



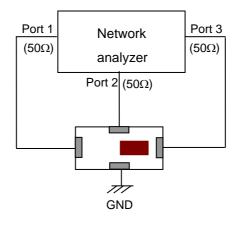
| Mark | L | W | Т | а | b | С | d |
|------------|-------|-------|-------|------|------|------|-------|
| Dimensions | 1.0 ± | 0.5 ± | 0.38± | 0.3± | 0.3± | 0.1± | 0.35± |
| Dimensions | 0.1 | 0.05 | 0.05 | 0.10 | 0.10 | 0.05 | 0.1 |



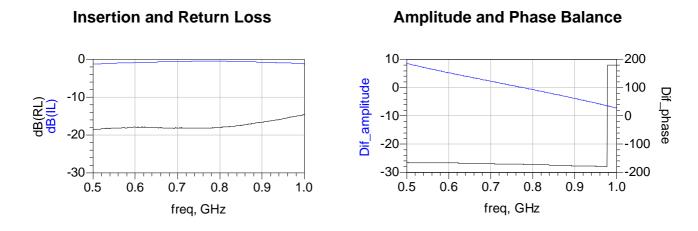


* Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Typical Electrical Characteristics (T=25°C)



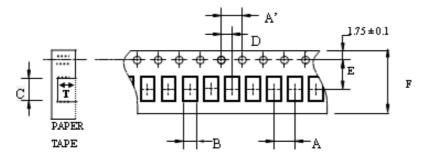
Notes

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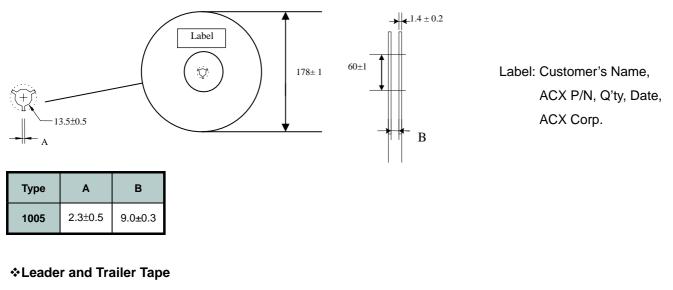
Taping Specifications

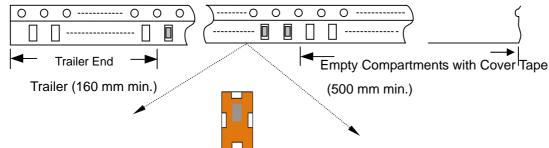
✤Tape Dimensions (Unit: mm) & Quantity



| Туре | Α | A' | В | С | D | E | F | т | Quantity/reel | Tape material |
|------|------|------|-------|-------|------|------|------|-------|---------------|---------------|
| 1005 | 2.0± | 4.0± | 0.62± | 1.12± | 2.0± | 3.5± | 8.0± | 0.45± | 10,000 | Dopor |
| 1005 | 0.05 | 0.1 | 0.03 | 0.03 | 0.05 | 0.05 | 0.1 | 0.03 | 10,000pcs | Paper |

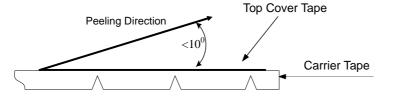
Reel Dimensions (Unit: mm)







*Peel-off Force



Peel-off force should be in the range of 0.1 - 0.6 N at a peel-off speed of 300 ± 10 mm/min .

Storage Conditions

- (1) Temperature: $5 \sim 35^{\circ}$ C, relative humidity (RH): $45 \sim 75$ %.
- (2) Non-corrosive environment.

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Mechanical & Environmental Characteristics

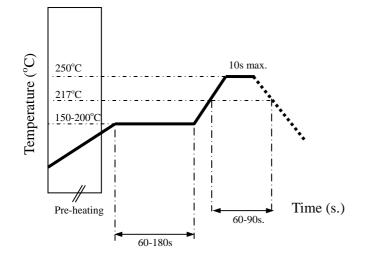
| Item | Requirements | Procedure |
|---|---|--|
| Solderability | No apparent damage More than 75% of the terminal electrode shall be covered with new solder. | Preheat: 120± 5 °C Solder: 245± 5 °C for 5± 1 sec |
| Soldering strength (Termination Adhesion) | 1. 3N minimum | Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction |
| Deflection (Substrate Bending) | No apparent damage Fulfill the electrical specification | Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection Pressure Rod R230 Pressure Rod 90mm 90mm |
| Heat/Humidity Resistance | No apparent damage Fulfill the electrical specification after test | Temperature: 85± 2°C Humidity: 90% ~ 95% RH Duration: 1000±48hrs Recovery: 1-2hrs |
| Thermal shock (Temperature Cycle) | No apparent damage Fulfill the electrical specification after test | One cycle/step 1 : 125 ± 5°C for 30 min step 2 : - 40 ± 5°C for 30 min No of cycles : 100 Recovery:1-2 hrs |
| Low Temperature Resistance | No apparent damage Fulfill the electrical specification after test | Temperature: -40± 5 °C Duration: 500 ±24hrs Recovery: 1-2hrs |



Soldering Conditions

*****Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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Advanced Ceramic X Corp. 16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan TEL:886-3-5987008 FAX:886-3-5987001 E-mail: acx@acxc.com.tw http://www.acxc.com.tw

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